



100V N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

BV _{DSS}	R _{DS(ON)} Max	I _D T _A = +25°C
100\/	15mΩ @ V _{GS} = 10V	8.9A
100V	18mΩ @ V _{GS} = 6.0V	7.9A

Features and Benefits

- 100% Unclamped Inductive Switch (UIS) Test in Production
- High Conversion Efficiency
- Low R_{DS(ON)} Minimizes On-State Losses
- Low Input Capacitance
- Fast Switching Speed
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Description and Applications

This new generation N-Channel Enhancement Mode MOSFET is designed to minimize $R_{DS(ON)}$, yet maintain superior switching performance. This device is ideal for use in notebook battery power management and load switch.

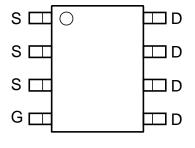
- Backlighting
- Power Management Functions
- DC-DC Converters

Mechanical Data

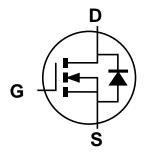
- Case: SO-8
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections Indicator: See Diagram
- Terminals: Finish Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 (3)
- Weight: 0.074 grams (Approximate)



Top View



Top View



Equivalent Circuit

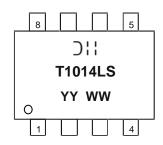
Ordering Information (Note 4)

Part Number	Case	Packaging
DMT10H014LSS-13	SO-8	2,500/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



T1014LS = Product Type Marking Code
YYWW = Date Code Marking
YY or YY = Year (ex: 16 = 2016)
WW = Week (01 to 53)



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			V_{DSS}	100	V
Gate-Source Voltage			V _{GSS}	±20	V
Continuous Drain Current (Note 6) V _{GS} = 10V	Steady State	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	I _D	8.9 7.1	А
Maximum Continuous Body Diode Forward Current (Note 6)			Is	3	Α
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)			I _{DM}	54	Α
Avalanche Current, L = 3mH			I _{AS}	7.5	Α
Avalanche Energy, L = 3mH			E _{AS}	85	mJ

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Total Power Dissipation (Note 5)	P_{D}	1.2	W
Thermal Resistance, Junction to Ambient (Note 5)	R _{0JA}	100	°C/W
Total Power Dissipation (Note 6)	P _D	1.67	W
Thermal Resistance, Junction to Ambient (Note 6)	$R_{\theta JA}$	75	°C/W
Thermal Resistance, Junction to Case (Note 6)	Reuc	12	°C/W
Operating and Storage Temperature Range	T _{J,} T _{STG}	-55 to +150	°C

Electrical Characteristics (T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)							
Drain-Source Breakdown Voltage	BV _{DSS}	100	_	_	V	$V_{GS} = 0V$, $I_D = 1mA$	
Zero Gate Voltage Drain Current	I _{DSS}	_	_	1	μΑ	$V_{DS} = 80V, V_{GS} = 0V$	
Gate-Source Leakage	IGSS	_	_	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 7)							
Gate Threshold Voltage	V _{GS(TH)}	1.4	2	3	٧	$V_{DS} = V_{GS}$, $I_D = 250\mu A$	
		_	11.5	15		$V_{GS} = 10V, I_D = 20A$	
Static Drain-Source On-Resistance	R _{DS(ON)}	_	15	18	mΩ	$V_{GS} = 6V, I_D = 20A$	
		_	17.5	25		$V_{GS} = 4.5V, I_D = 5A$	
Diode Forward Voltage	V_{SD}	_	0.9	1.3	V	$V_{GS} = 0V, I_{S} = 20A$	
DYNAMIC CHARACTERISTICS (Note 8)							
Input Capacitance	C _{iss}	_	1871	_		V _{DS} = 50V, V _{GS} = 0V f = 1MHz	
Output Capacitance	Coss	1	261	_	pF		
Reverse Transfer Capacitance	C _{rss}		7	_			
Gate Resistance	R_{G}	_	0.75	_	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$	
Total Gate Charge	Qg	_	33.3	_			
Gate-Source Charge	Q _{gs}	_	6.9	_	nC	$V_{DD} = 50V, I_{D} = 10A,$ $V_{GS} = 10V$	
Gate-Drain Charge	Q _{gd}	_	5.1	_			
Turn-On Delay Time	t _{D(ON)}	_	6.5	_		$V_{DD} = 50V, V_{GS} = 10V,$ $I_{D} = 10A, R_{G} = 6\Omega$	
Turn-On Rise Time	t _R	_	7	_			
Turn-Off Delay Time	t _{D(OFF)}	_	19.7	_	ns		
Turn-Off Fall Time	t _F	_	8.1	_			
Reverse Recovery Time	t _{RR}	_	37.9	_	ns	100 11/11 1000/	
Reverse Recovery Charge	Q_{RR}	_	51.9	_	nC	$I_F = 10A$, $di/dt = 100A/\mu s$	

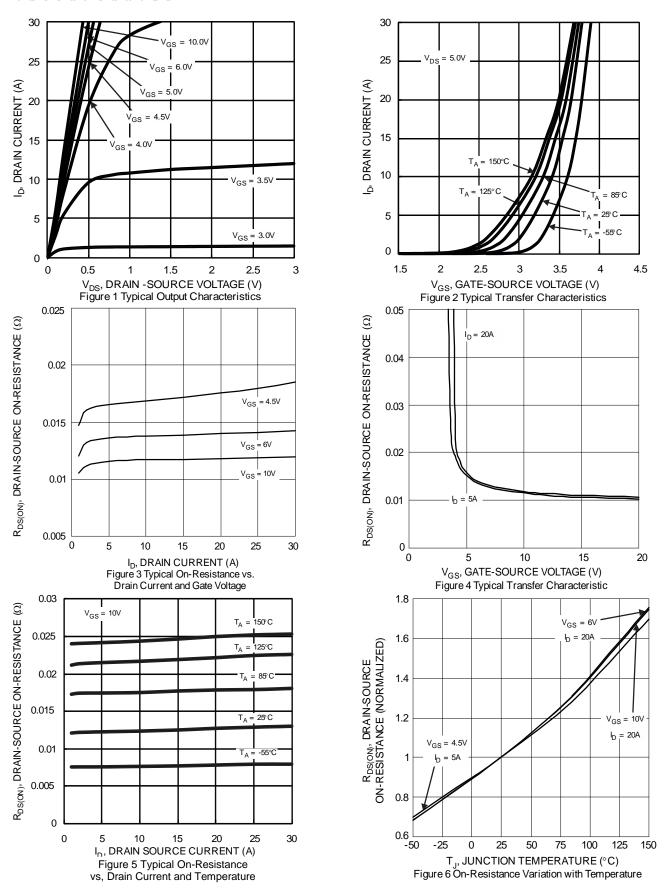
Notes: 5. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.

^{6.} Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.

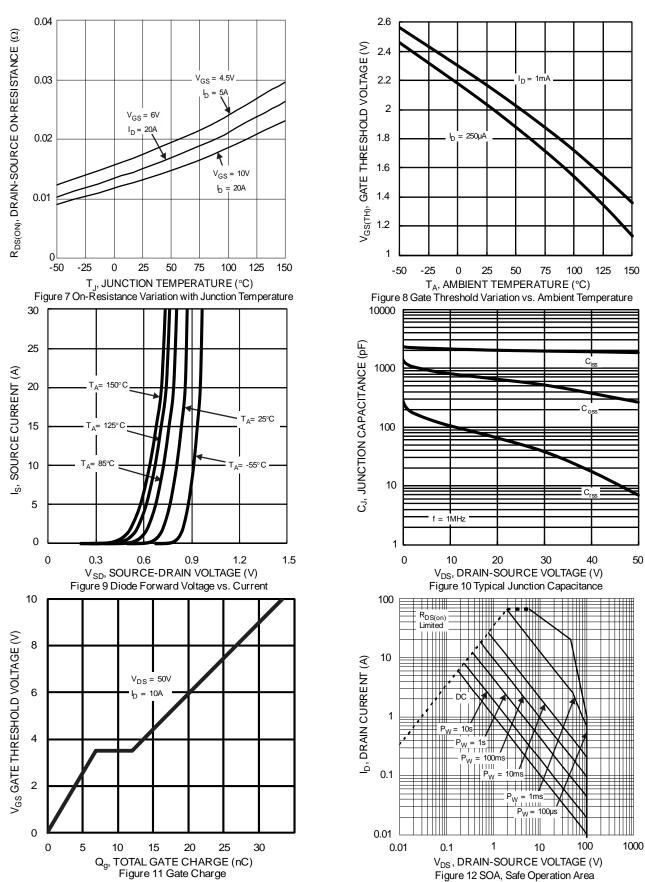
^{7.} Short duration pulse test used to minimize self-heating effect.

^{8.} Guaranteed by design. Not subject to product testing.

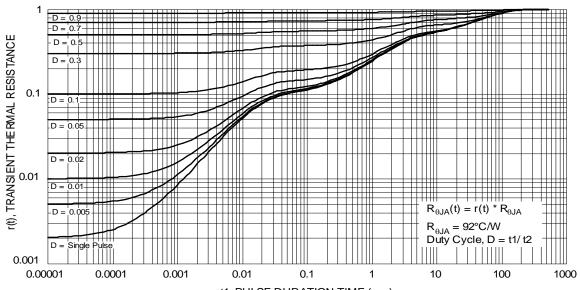












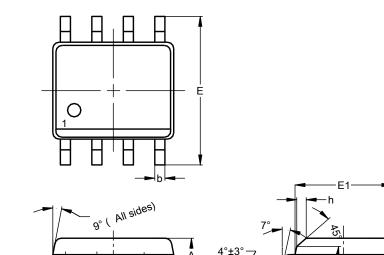
t1, PULSE DURATION TIME (sec) Figure 13 Transient Thermal Resistance



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

SO-8



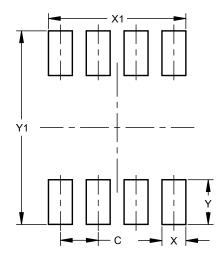
SO-8					
Dim	Min	Max	Тур		
Α	1.40	1.50	1.45		
A1	0.10	0.20	0.15		
b	0.30	0.50	0.40		
С	0.15	0.25	0.20		
D	4.85	4.95	4.90		
Е	5.90	6.10	6.00		
E1	3.80	3.90	3.85		
E0	3.85	3.95	3.90		
е			1.27		
h	-		0.35		
L	0.62	0.82	0.72		
Q	0.60	0.70	0.65		
All Dimensions in mm					

Suggested Pad Layout

40.1°

Please see http://www.diodes.com/package-outlines.html for the latest version.





Dimensions	Value (in mm)
C	1.27
Х	0.802
X1	4.612
Y	1.505
V1	6.50

Gauge Plane



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